

REMARKS

Reconsideration of this application is respectfully requested in view of the foregoing amendment and the following remarks.

Claims 1-20 were pending. Claims 9-11, 13, 15, and 19 have amended and claim 21 have been newly added. Accordingly, claims 1-21 will be pending herein upon entry of this Amendment. Support for the amendment to each of the claims and new claim 21 can be found, for example, at page 18, line 16 to page 20, line 5, and Figures 6A – 6C of the present application. For the reasons stated below, Applicants respectfully submit that all claims pending in this application are in condition for allowance.

In the Office Action mailed September 10, 2004, claims 1-8 were allowed but claims 9-20 were rejected under 35 U.S.C. §112, second paragraph, as being incomplete for omitting essential steps. To the extent the ground of rejections might still be applied to claims presently pending in this application, it is respectfully traversed.

Amended claim 9 now recites, among other things, depositing an electrode plate layer material on a top surface of said core dielectric layer filling said first plurality of via holes and forming a first plurality of vias, patterning and etching the electrode plate layer material to form a plurality of electrode plates and a plurality of middle ground shielding layers, wherein each of the plurality of electrode plates connects to each of the first plurality of vias; depositing a metal layer on a bottom surface of the core dielectric layer; and laminating a first dielectric layer onto the top surface of the plurality of middle ground shielding layers and the plurality of electrode plates and forming a second plurality of via holes therethrough, each of the second plurality of

via holes communicating with one of the plurality of electrode plates and the middle ground shielding layer.

Applicants believe that amended claim 9 has clearly disclosed their invention. For example, amended claim 9 clearly discloses that by patterning and etching the electrode plate layer material, a plurality of electrode plates and a plurality of middle ground shielding layers are formed on the top of the core dielectric layer. Therefore, the feature that each of the second plurality of via holes communicates with one of the plurality of electrode plates and the middle ground shielding layer has support.

Accordingly, Applicants respectfully submit that amended claim 9 and its dependent claims 10-14 have overcome the rejection of U.S.C. §112, second paragraph.

Applicants believe the Office Action failed to explain why claims 15-20 should be rejected. Claim 15 relates to an embedded microelectronic capacitor incorporating ground shielding layers that has similar features to those of allowed claim 1. Applicants have carefully reviewed claims 15-20 and made minor changes to claim 15 and 19, and added new claim 21. It is, thus, believed that amended claim 15 and its dependent claims are patentable.

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In view of the foregoing all of the claims in this case are believed to be in condition for allowance. Should the Examiner have any questions or determine that any further action is desirable to place this application in even better condition for issue, the Examiner is encouraged to telephone applicants' undersigned representative at the number listed below.

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Respectfully submitted,

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